

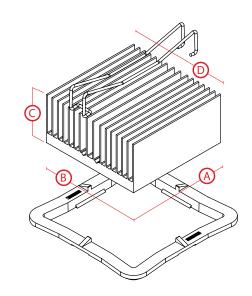
High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-53330D-C2-R0

Features & Benefits

- » High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Designed specifically for BGAs and other surface mount packages
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards
- » Comes preassembled with high performance, phase changing, thermal interface material

Thermal Performance





*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	11.1	5	
300	1.5	8.1		
400	2.0	6.8		
500	2.5	6		
600	3.0	5.4		
700	3.5	5		
800	4.0	4.7		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
33 mm	33 mm	9.5 mm	33 mm	SAINT-GOBAIN C1100F	BLACK-ANODIZED

NOTES:

 ATS-53330D-C1-R0 is a subsitute item available utilizing an equivalent phase change material (Chomerics T766).

3) Thermal performance data are provided for reference only. Actual performance may vary

- by application.
 ATS reserves the right to update or change its products without notice to improve the design or performance.
- 5) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT330
- 6) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

¹⁾ Dimension C = heat sink height from bottom of the base to the top of the fin field.